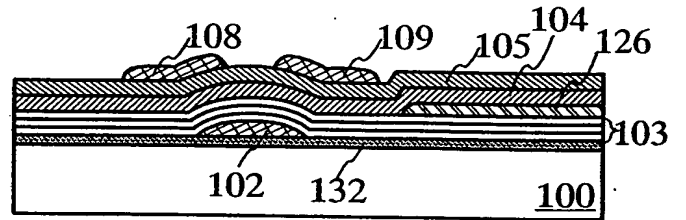


**FIG.1B**

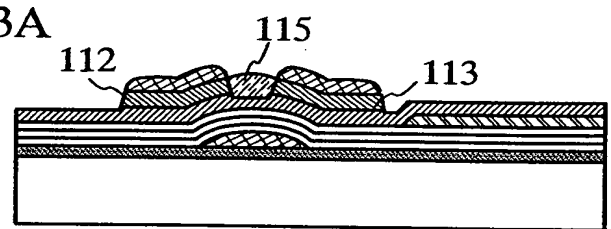
Diagram illustrating a second embodiment of the first circuit. The circuit includes two vertical lines, 1605 and 1607, and a horizontal line 1604. A first transistor 1601 is connected between 1605 and 1604. A second transistor 1602 is connected between 1607 and 1604. A load 1603 is connected to the output of transistor 1602. A capacitor is connected between 1604 and 1607.

Fig.2B



Y:

FIG.3A



**FIG.3B**

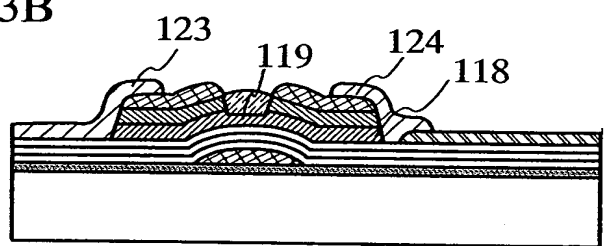


FIG.3C

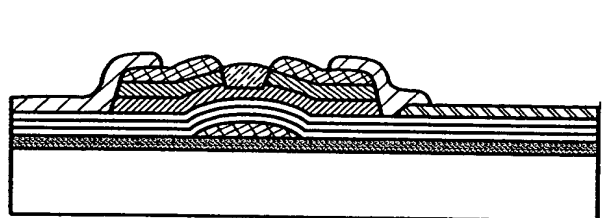


FIG.3D

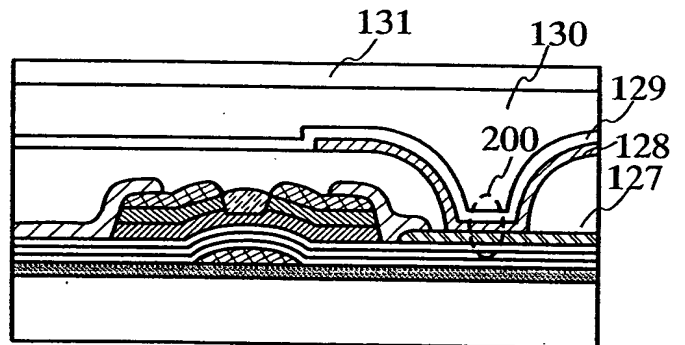


FIG.3E

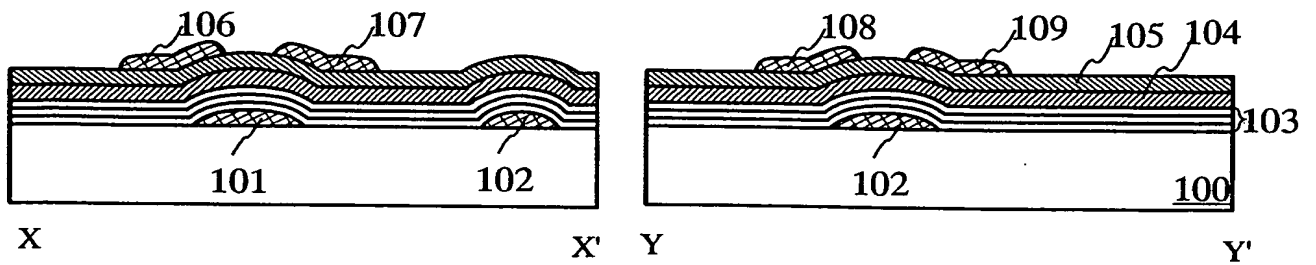


FIG. 4A

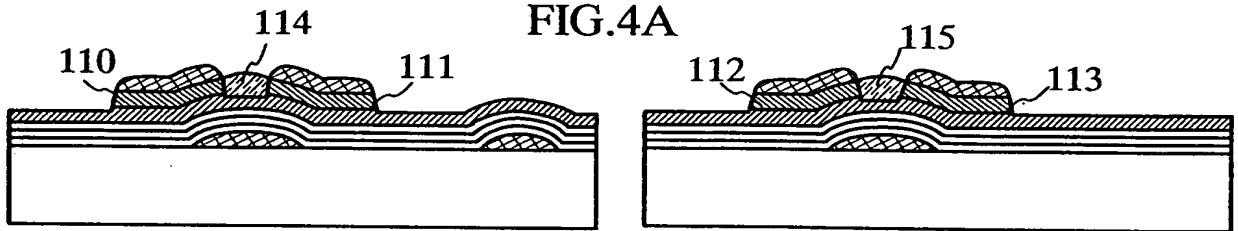


FIG. 4B

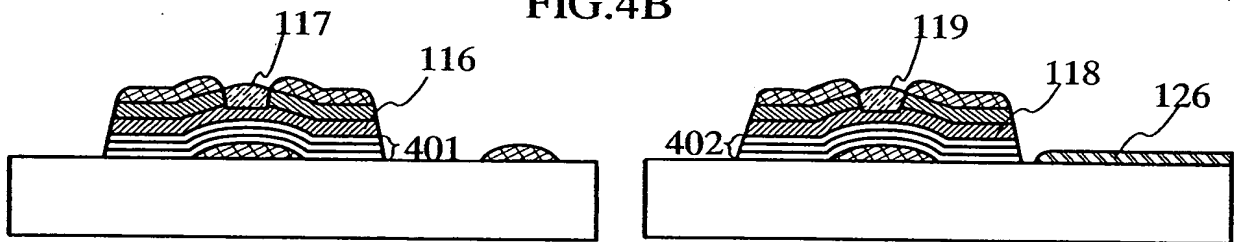


FIG. 4C

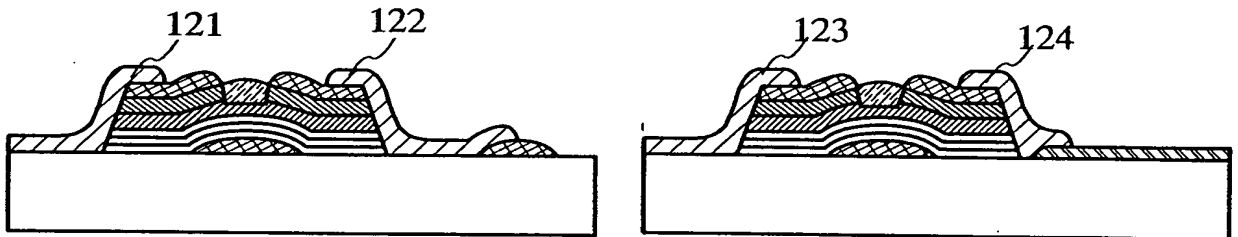


FIG. 4D

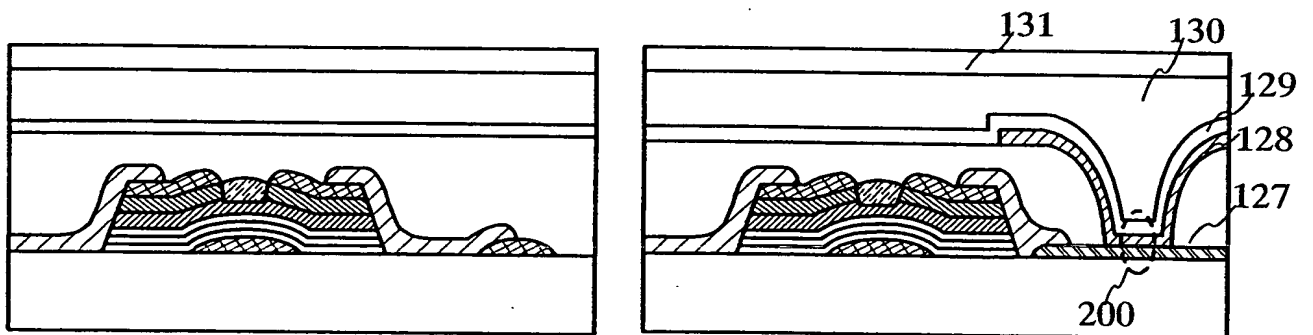


FIG. 4E

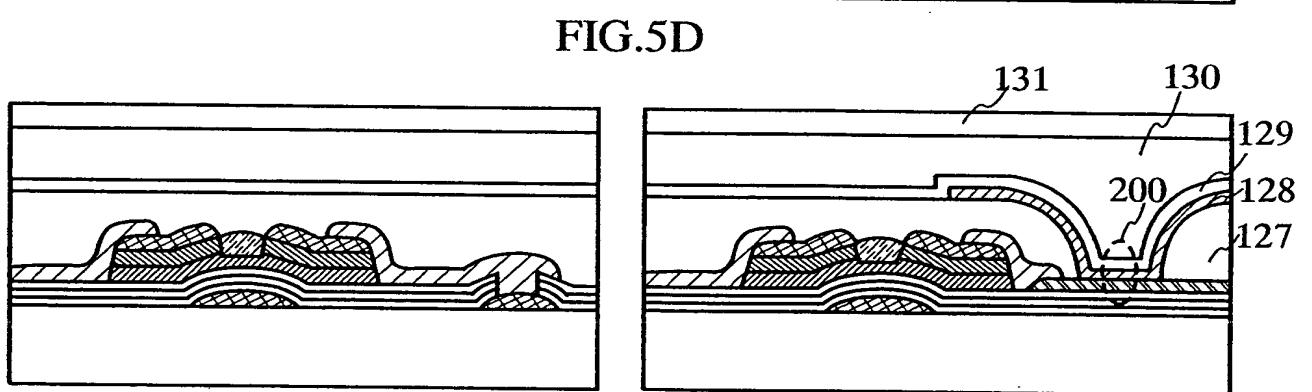
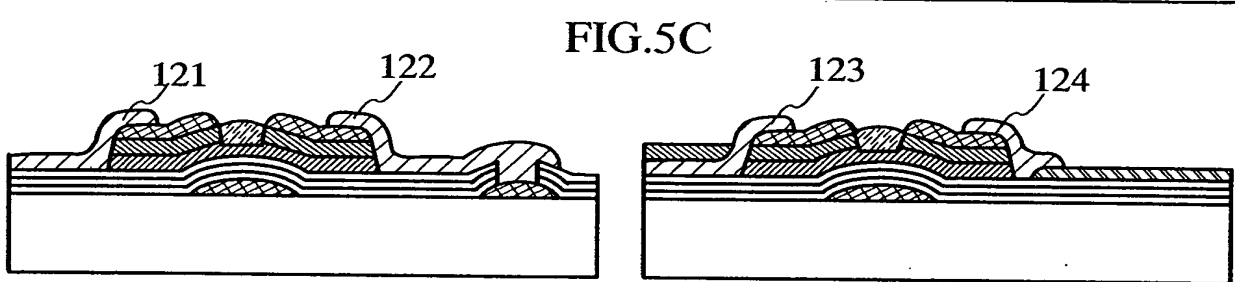
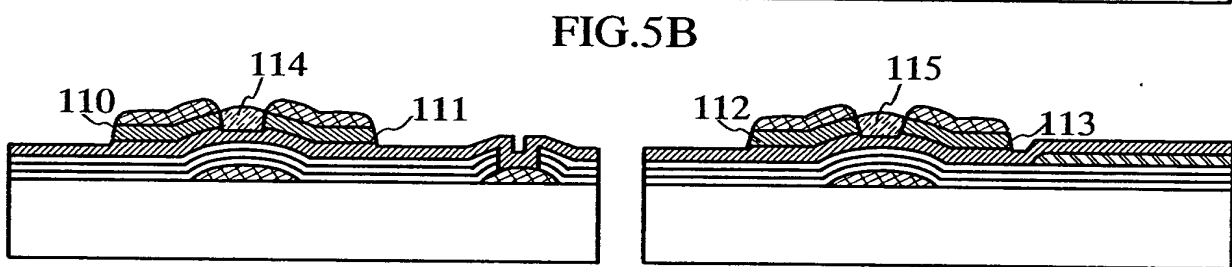
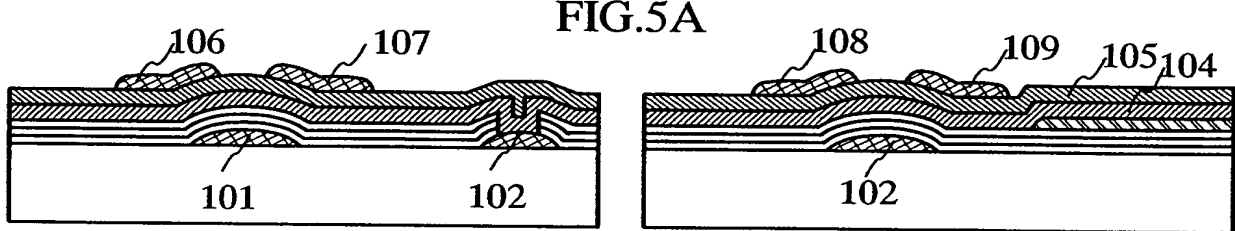
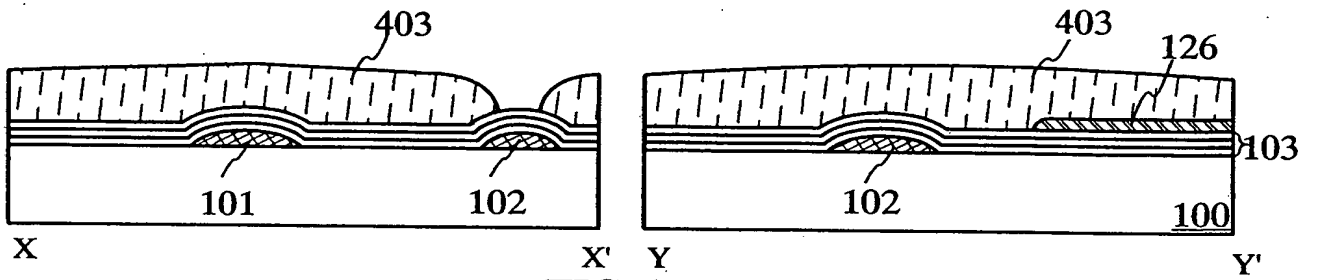


FIG. 5E

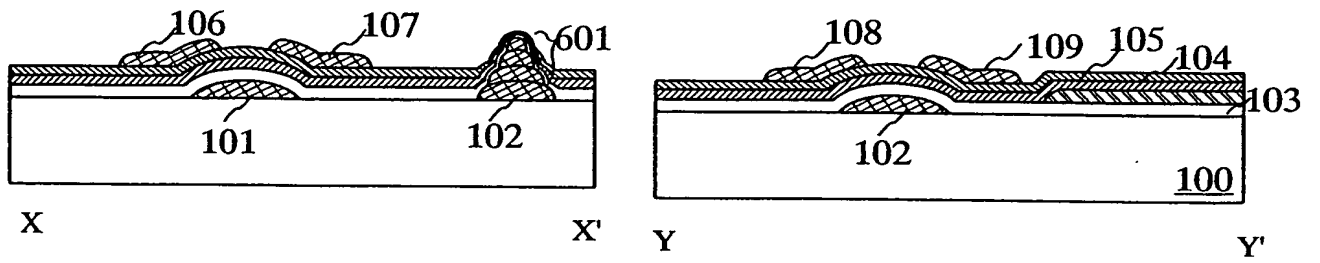


FIG. 6A

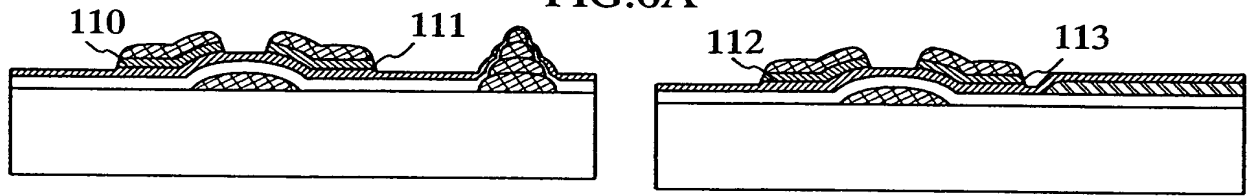


FIG. 6B

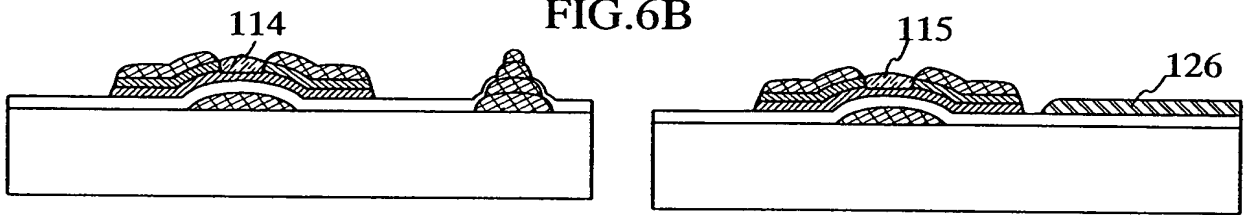


FIG. 6C

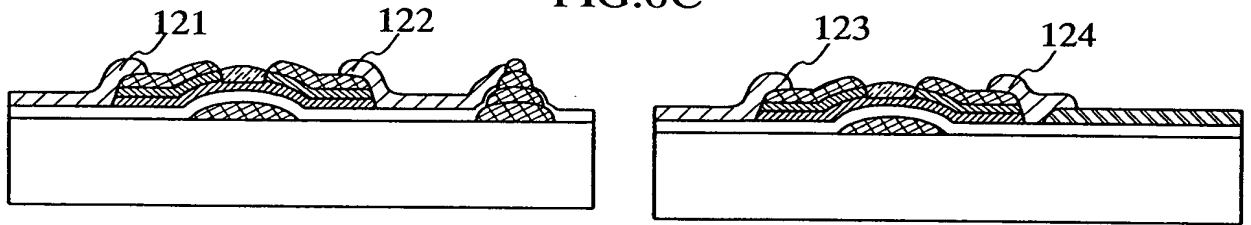


FIG. 6D

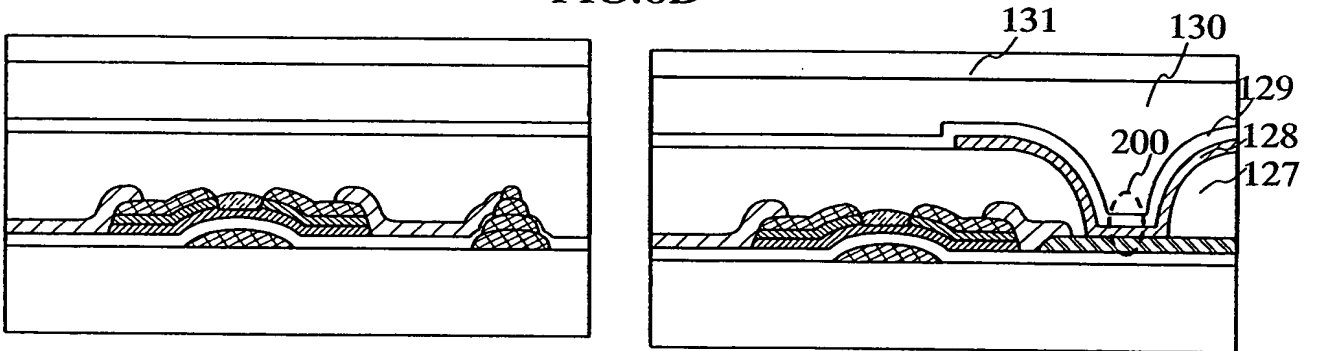


FIG. 6E

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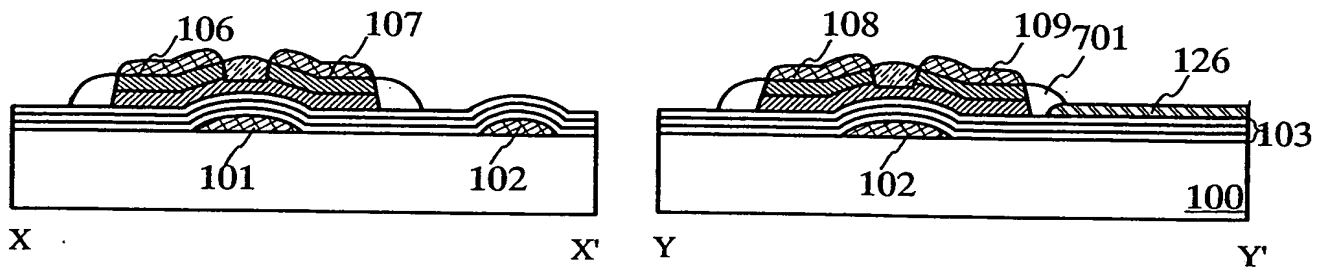


FIG. 7A

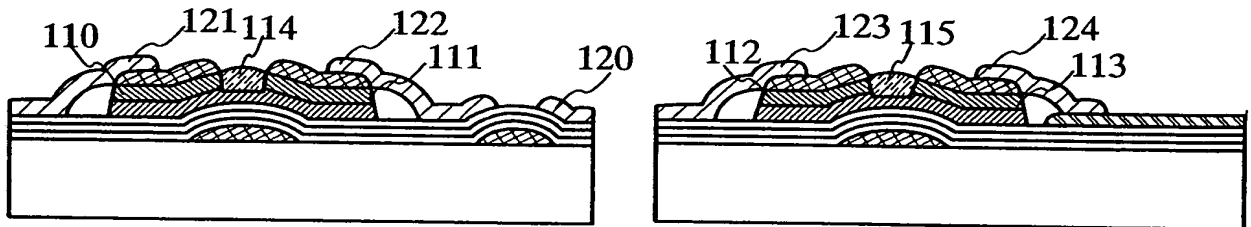


FIG. 7B

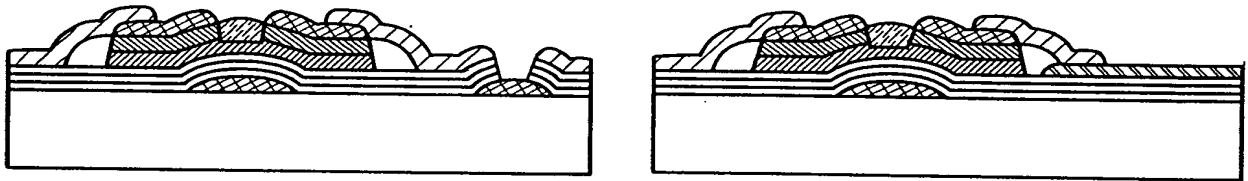


FIG. 7C

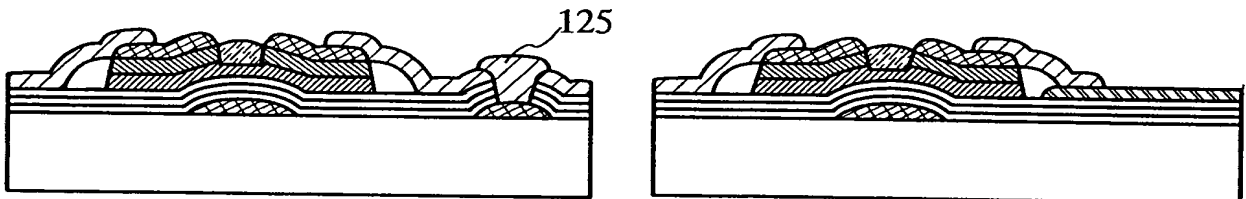


FIG. 7D

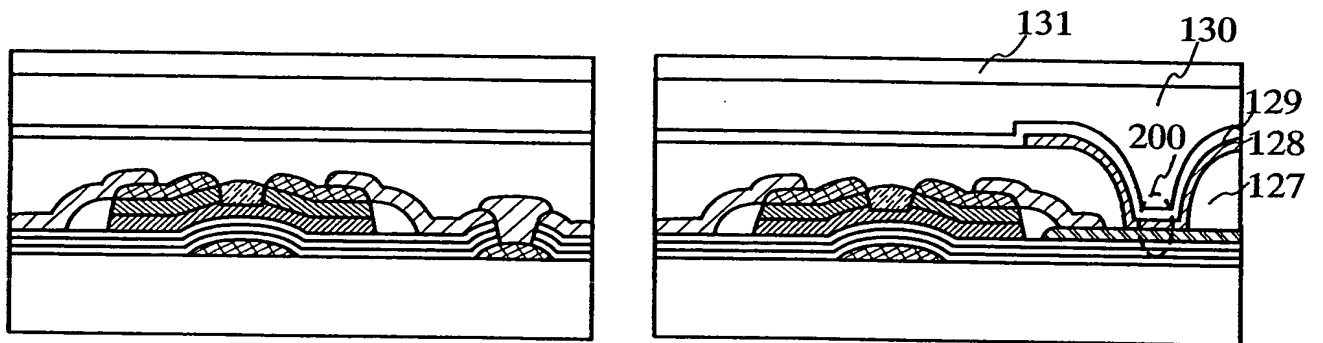


FIG. 7E

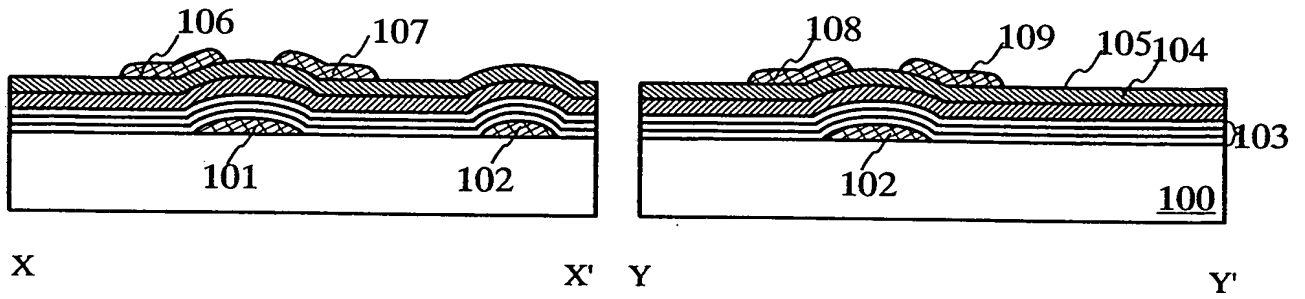


FIG. 8A

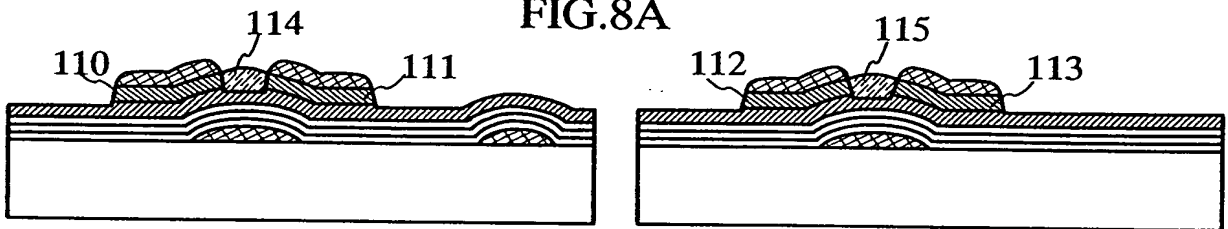


FIG. 8B

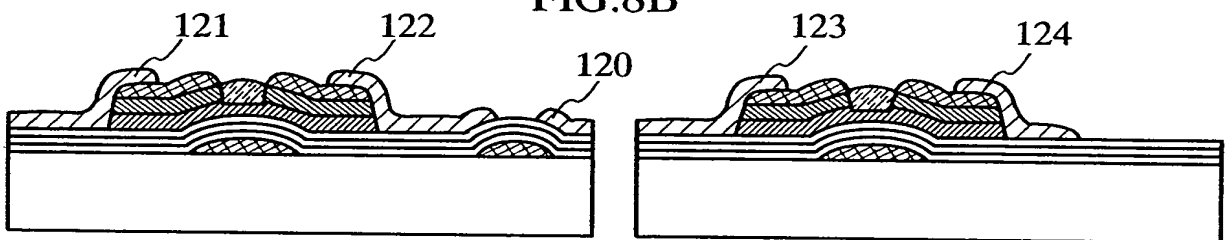


FIG. 8C

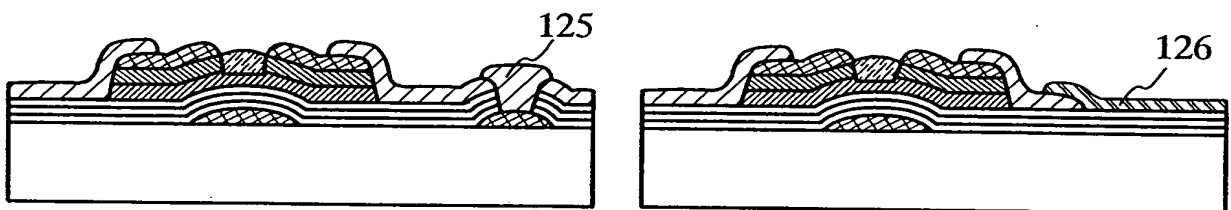


FIG. 8D

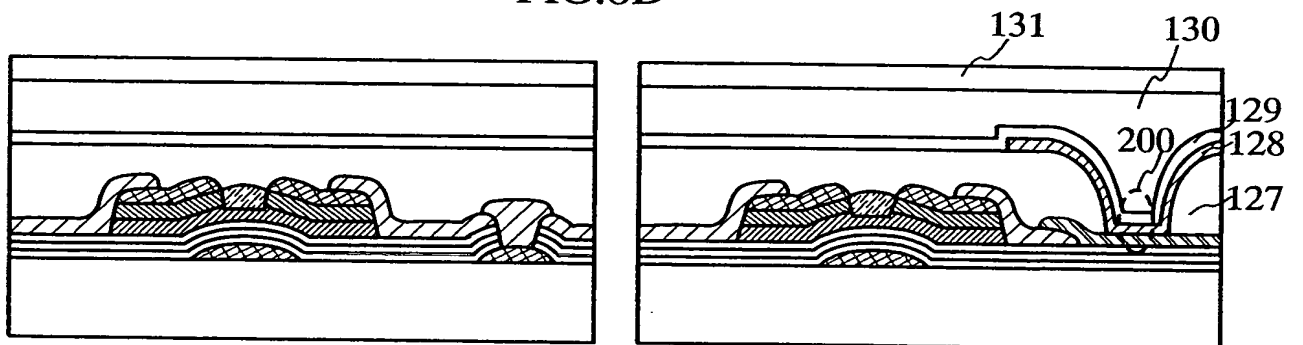


FIG. 8E

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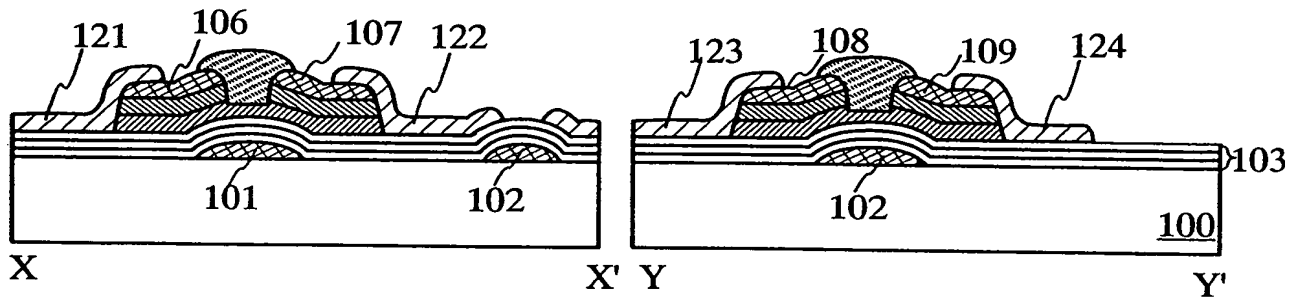


FIG. 9A

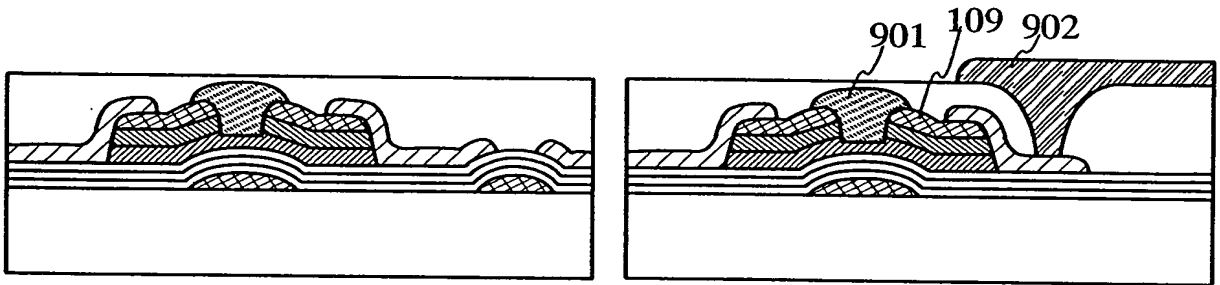


FIG. 9B

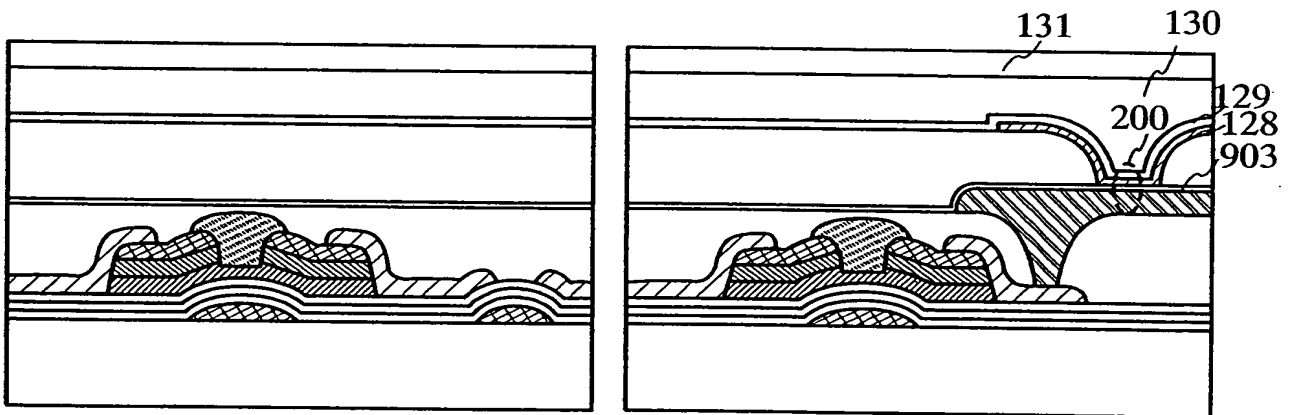


FIG. 9C

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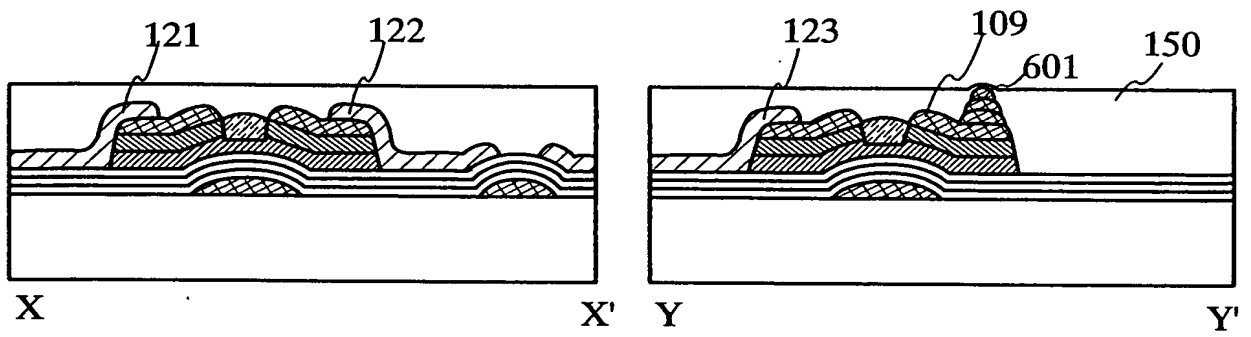


FIG. 10A

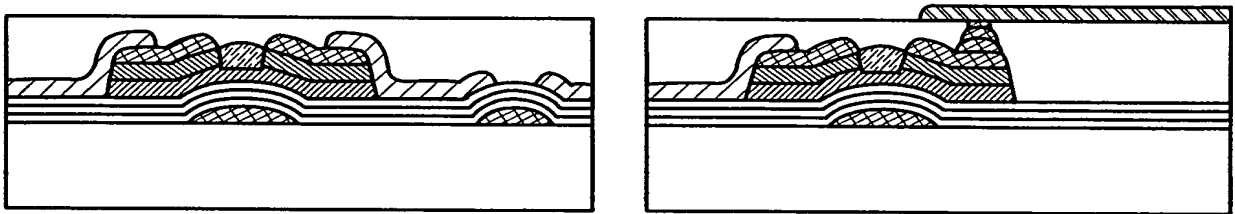


FIG. 10B

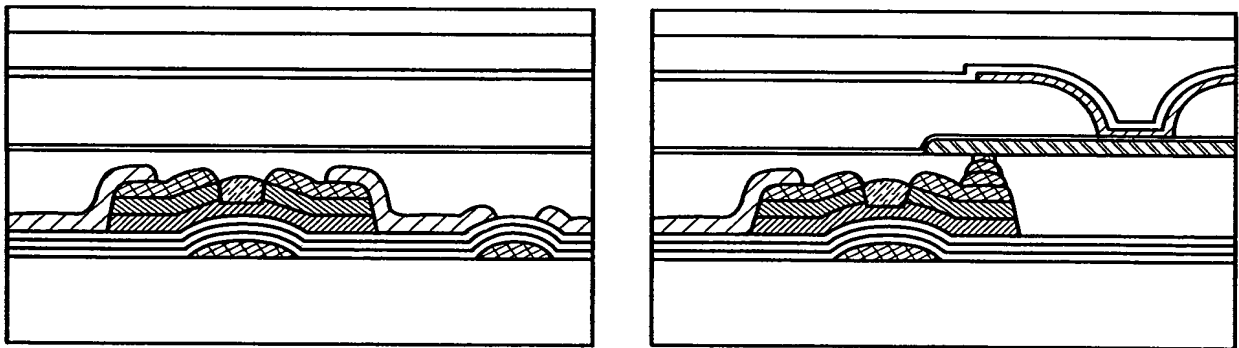
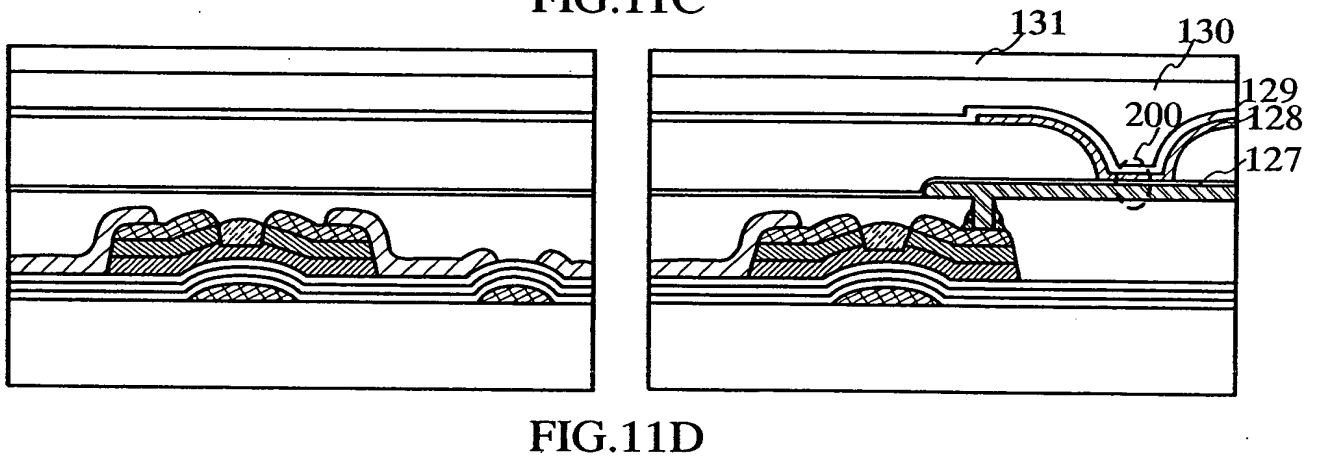
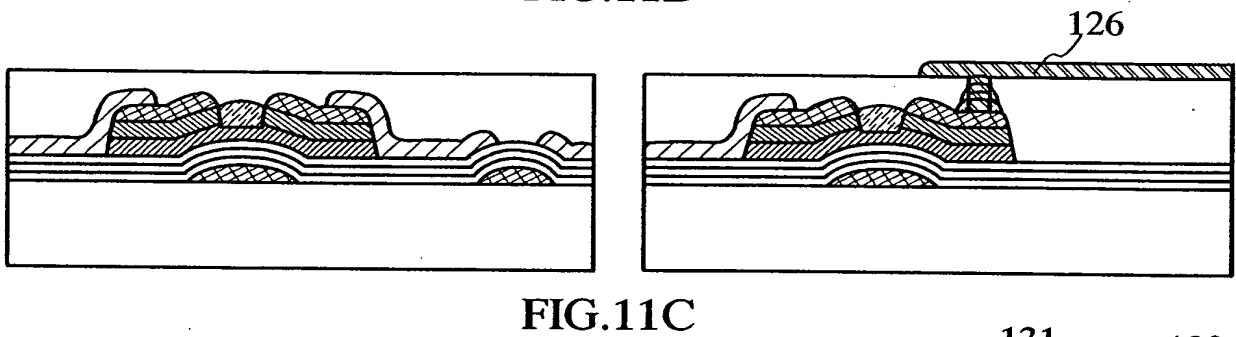
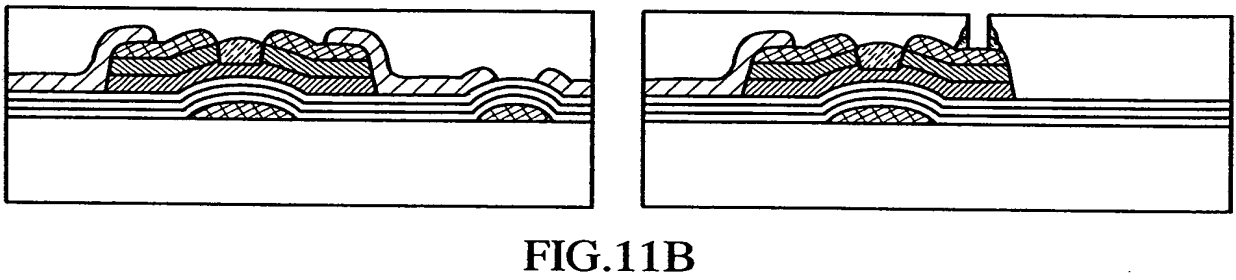
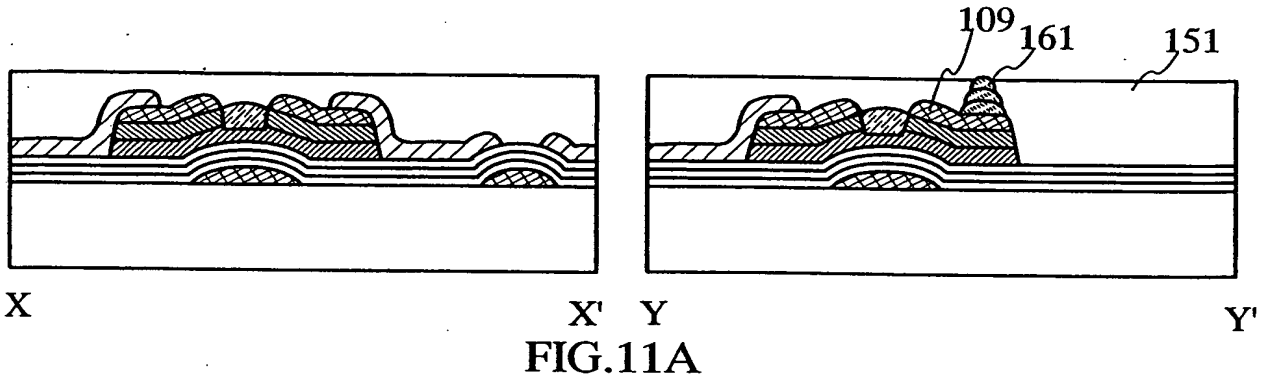


FIG. 10C



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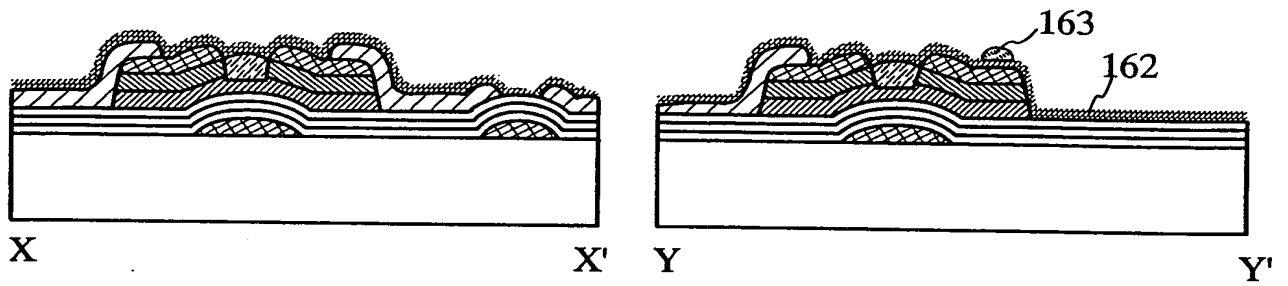


FIG. 12A

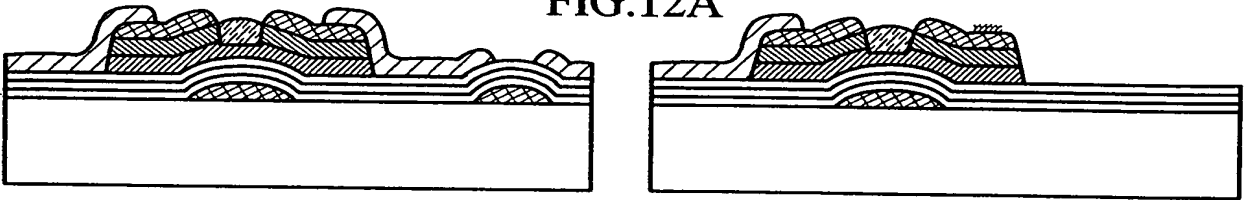


FIG. 12B

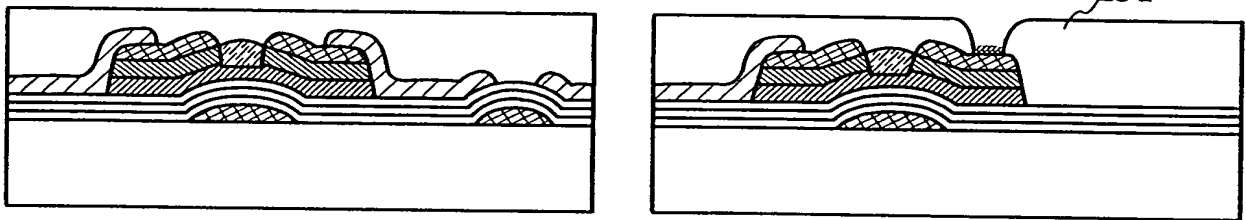


FIG. 12C

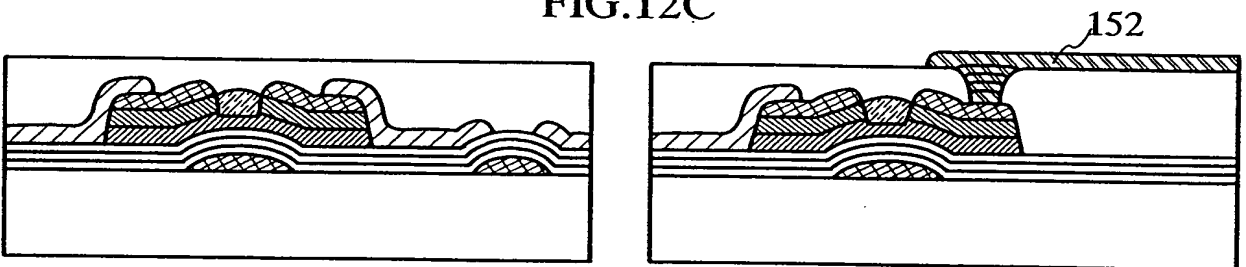


FIG. 12D

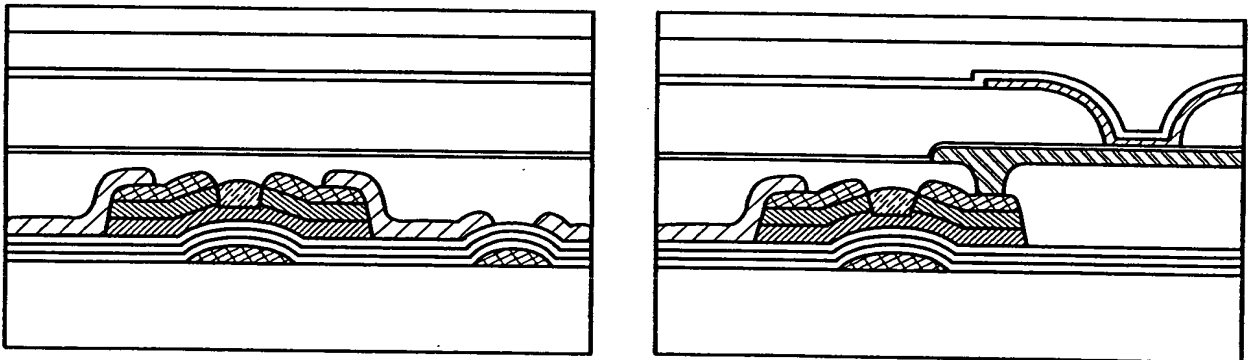


FIG. 12E

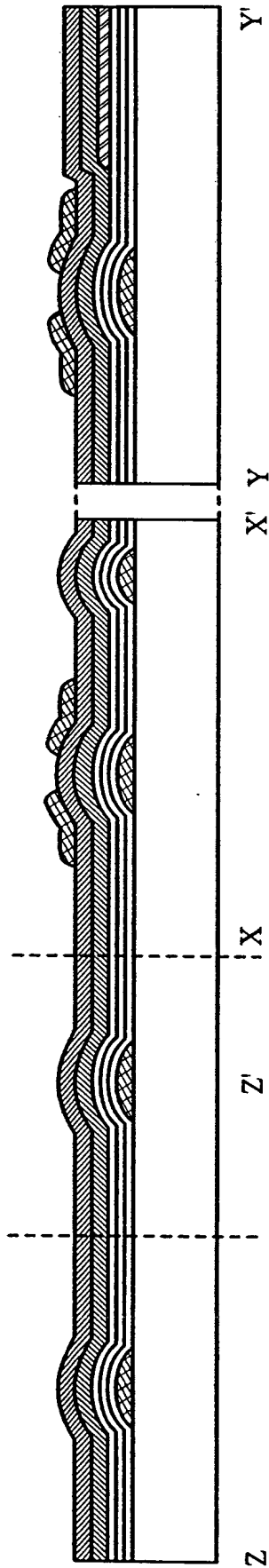


FIG. 13A

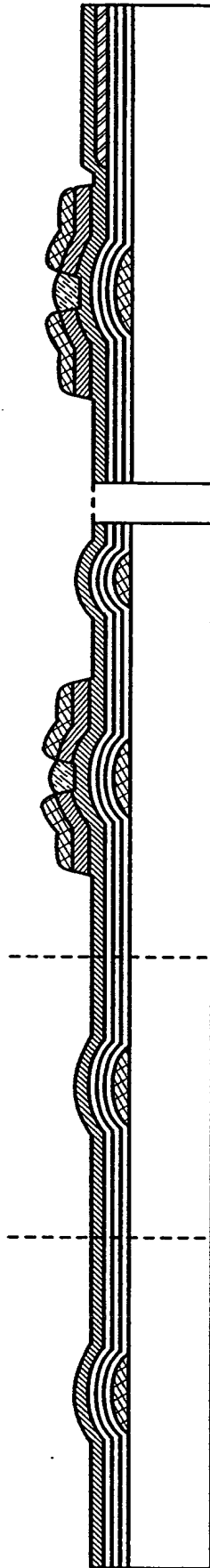


FIG. 13B

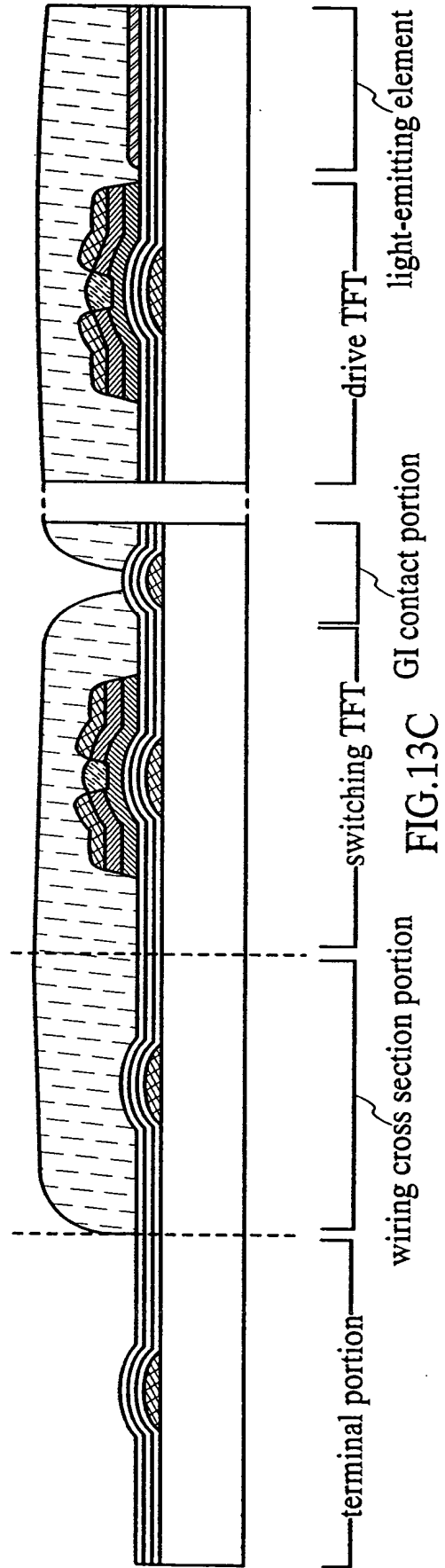
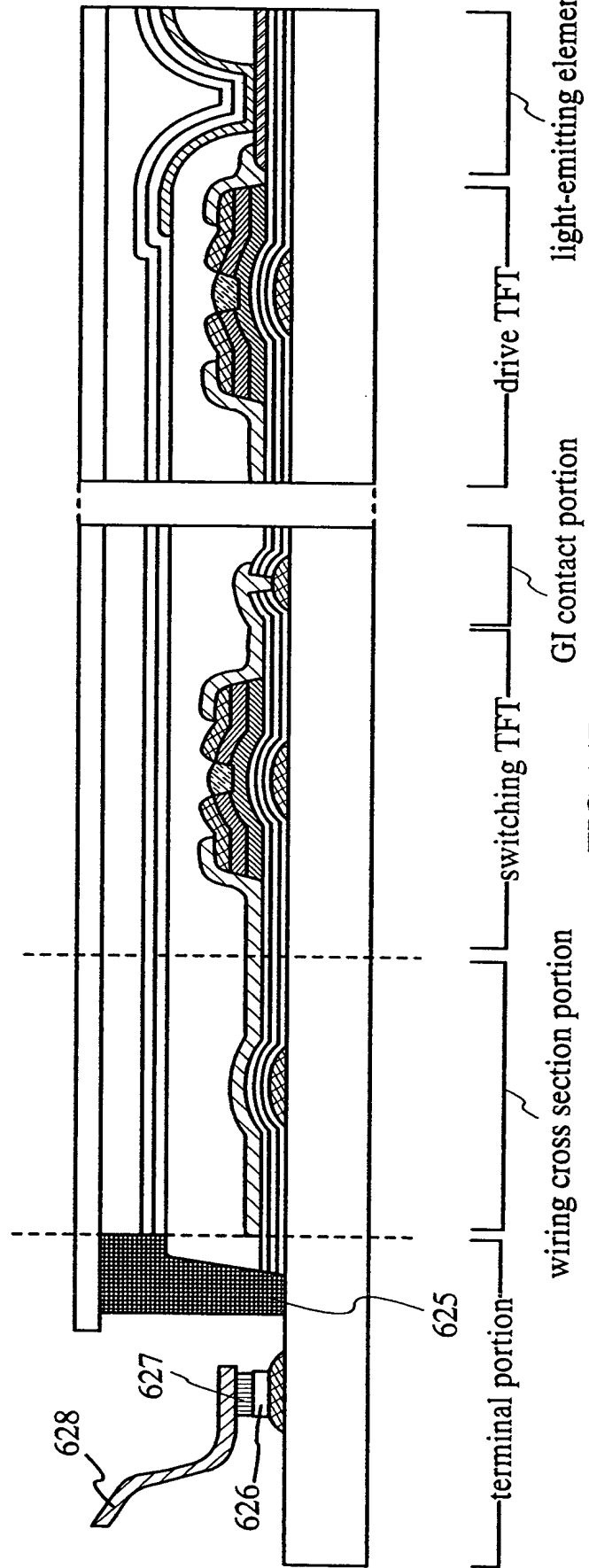
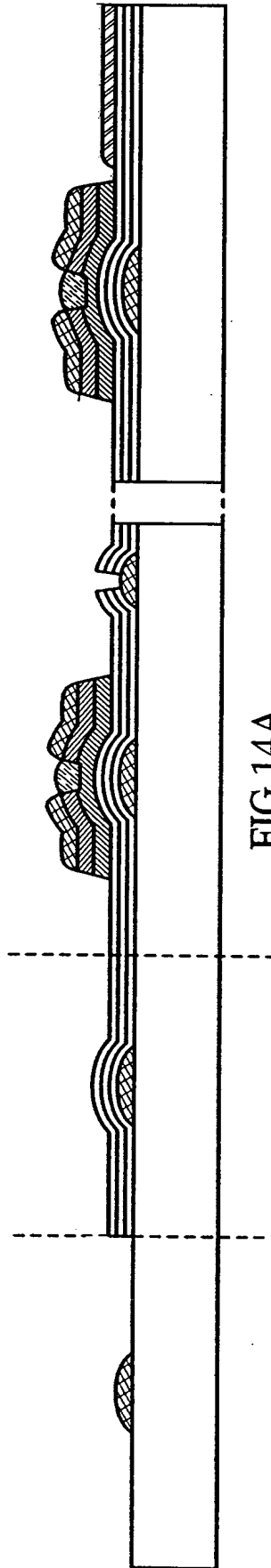


FIG. 13C



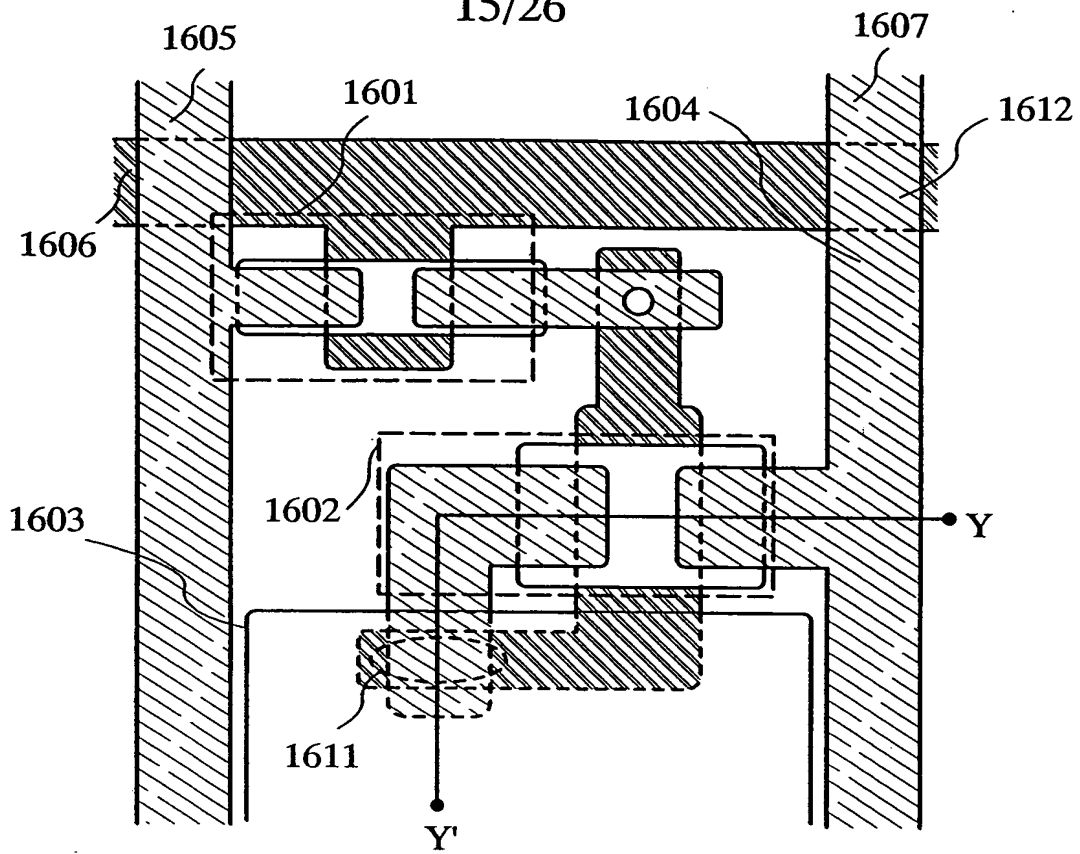


FIG.15A

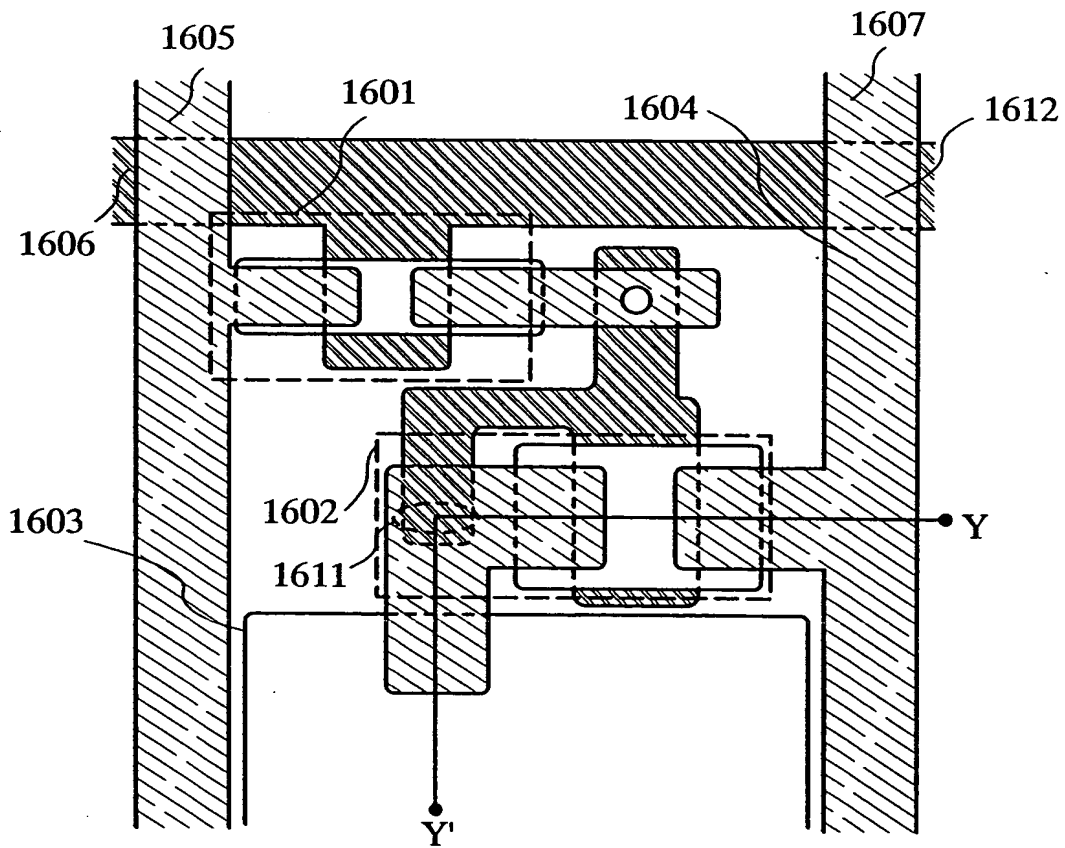


FIG.15B

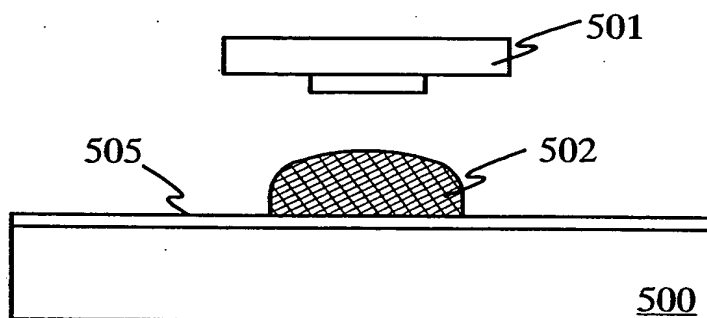


FIG. 16A

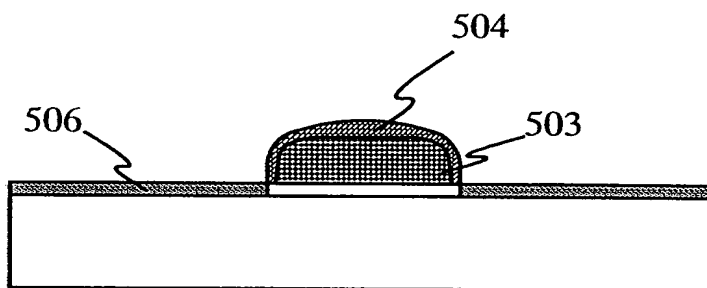
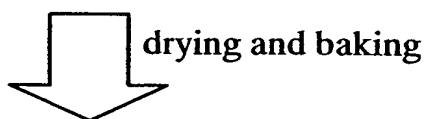


FIG. 16B

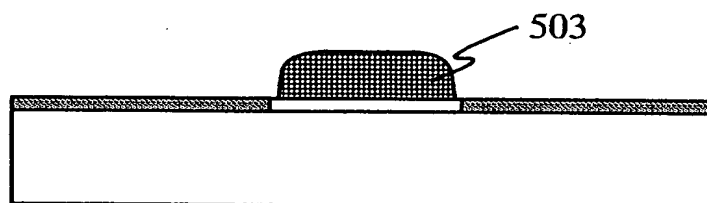
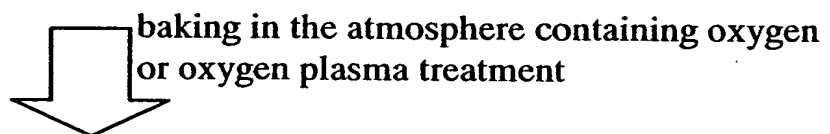


FIG. 16C

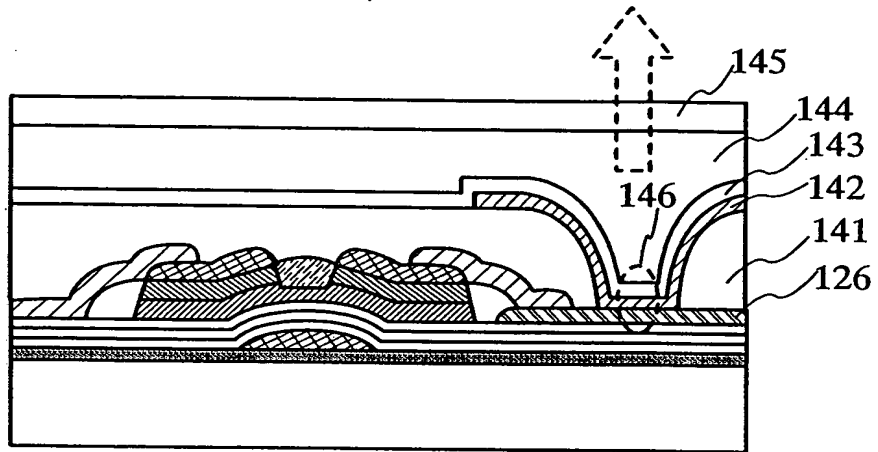


FIG. 17A

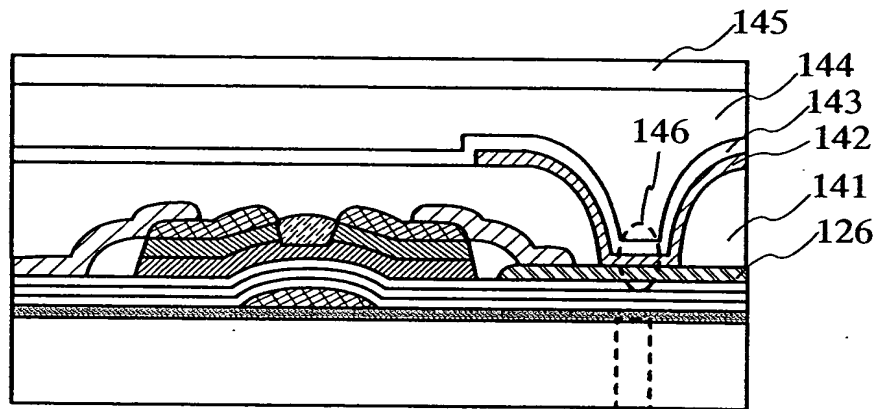


FIG. 17B

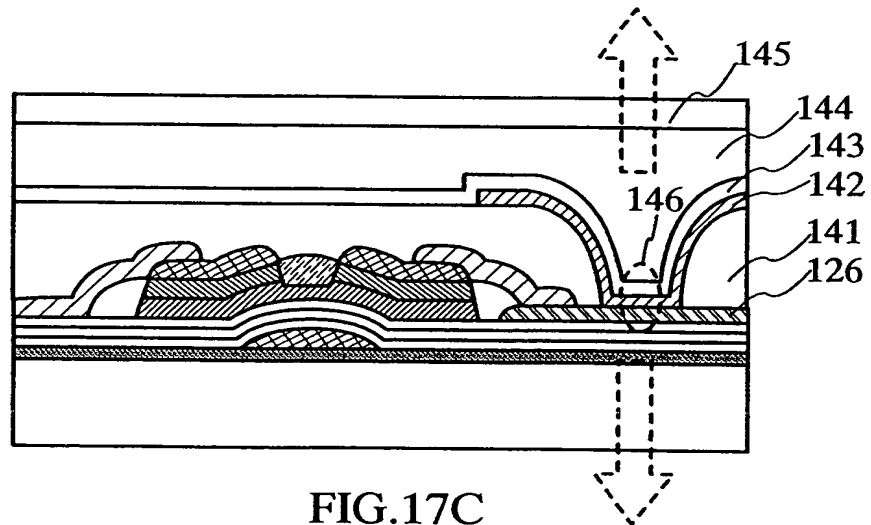


FIG. 17C

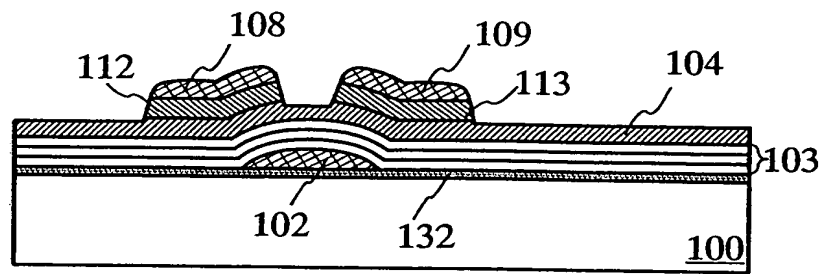


FIG. 18A

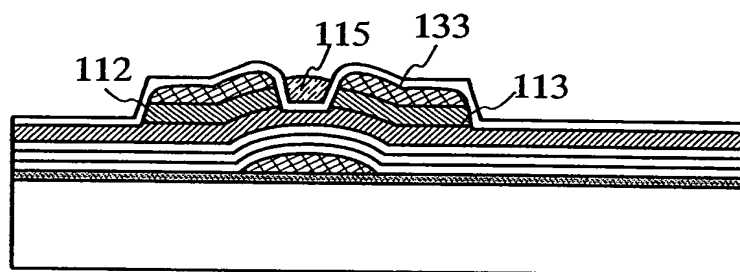


FIG. 18B

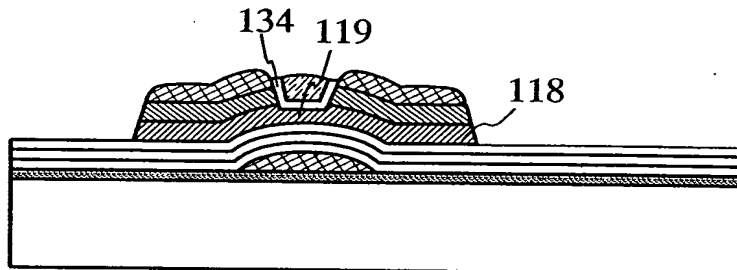


FIG. 18C

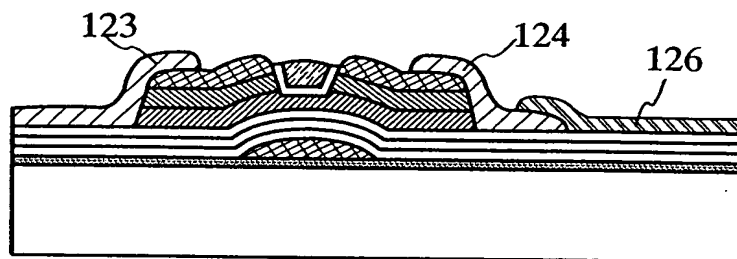


FIG. 18D

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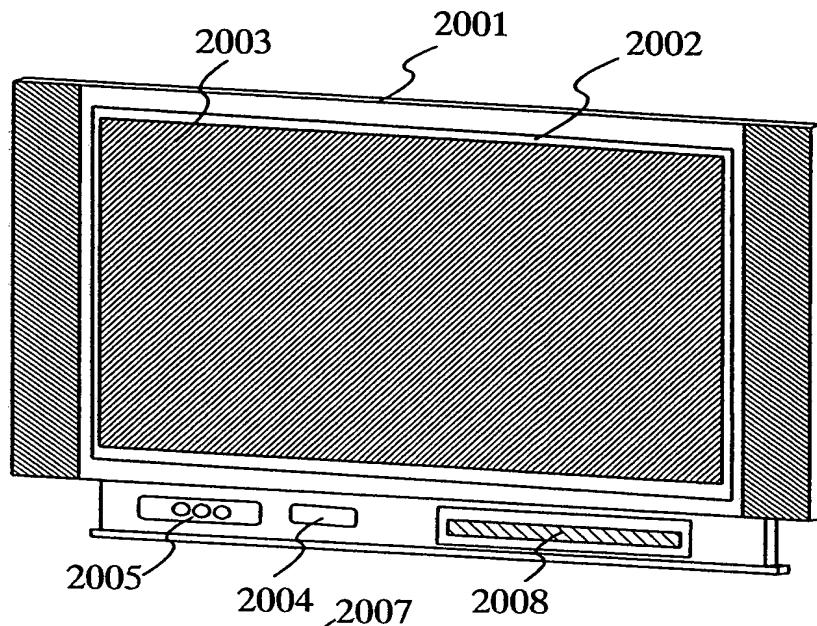


FIG. 19A

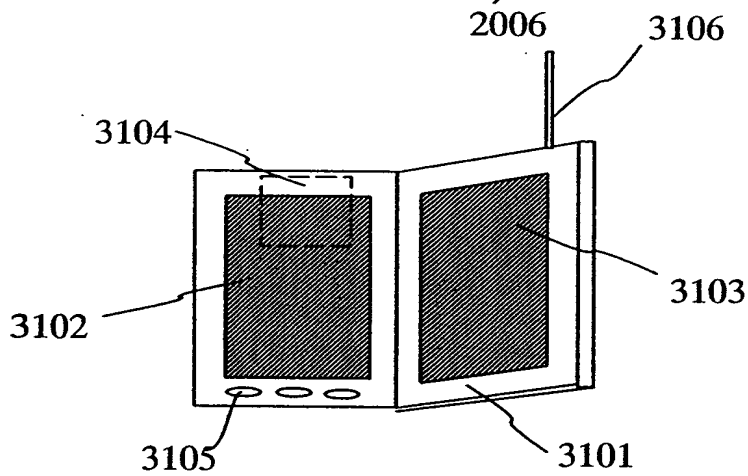


FIG. 19B

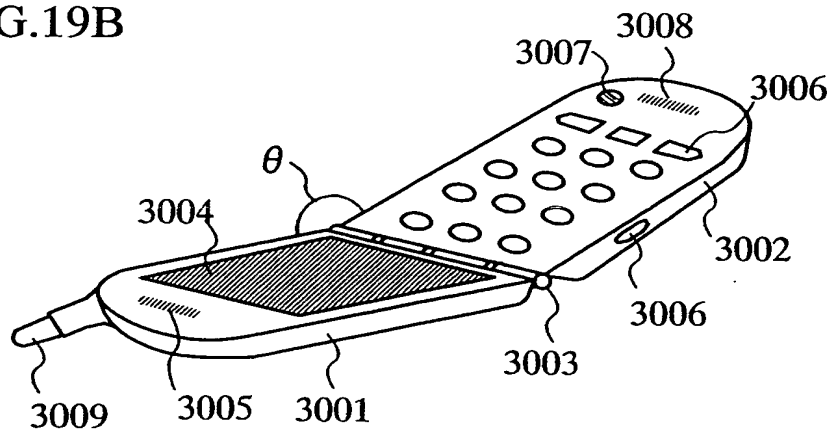
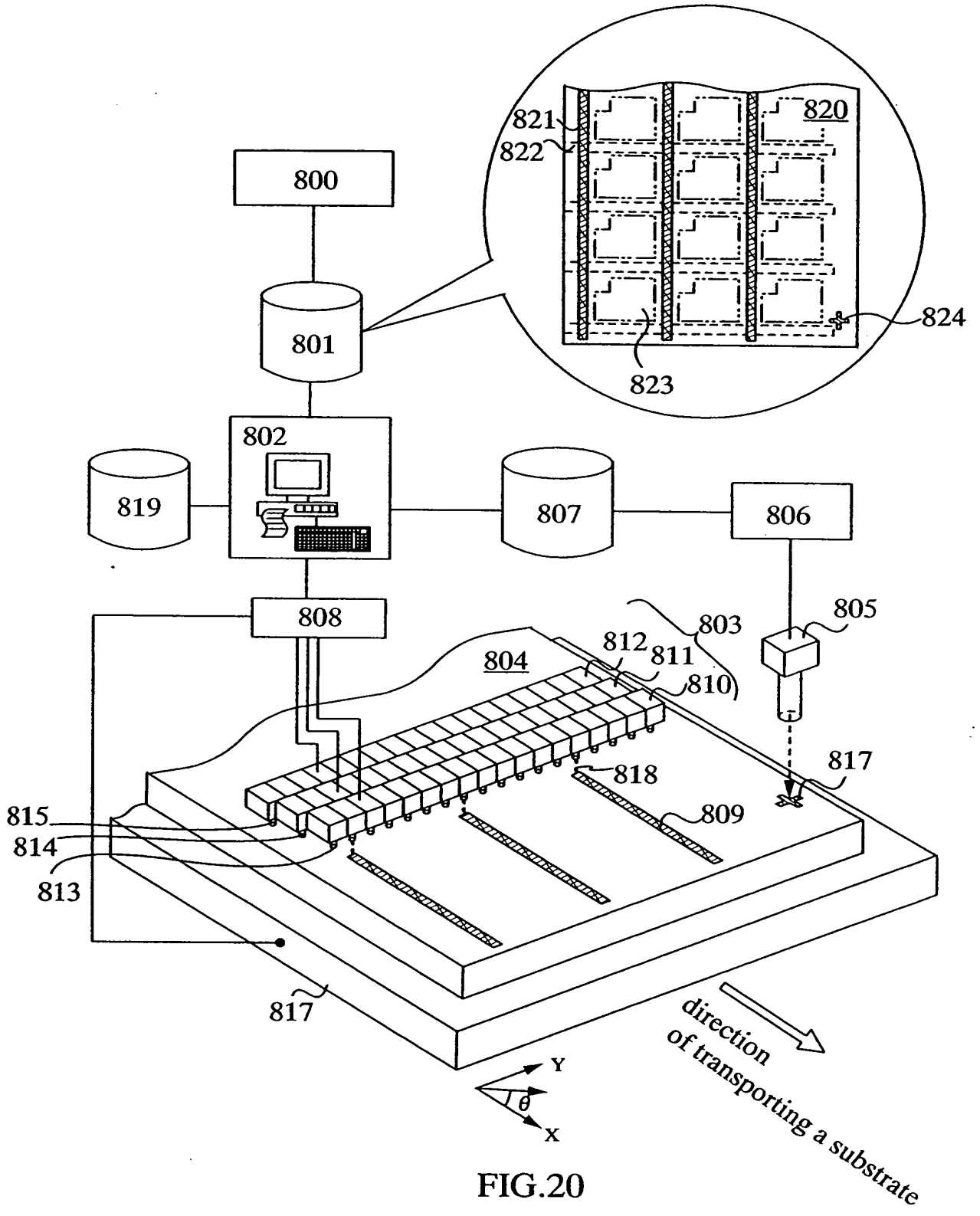
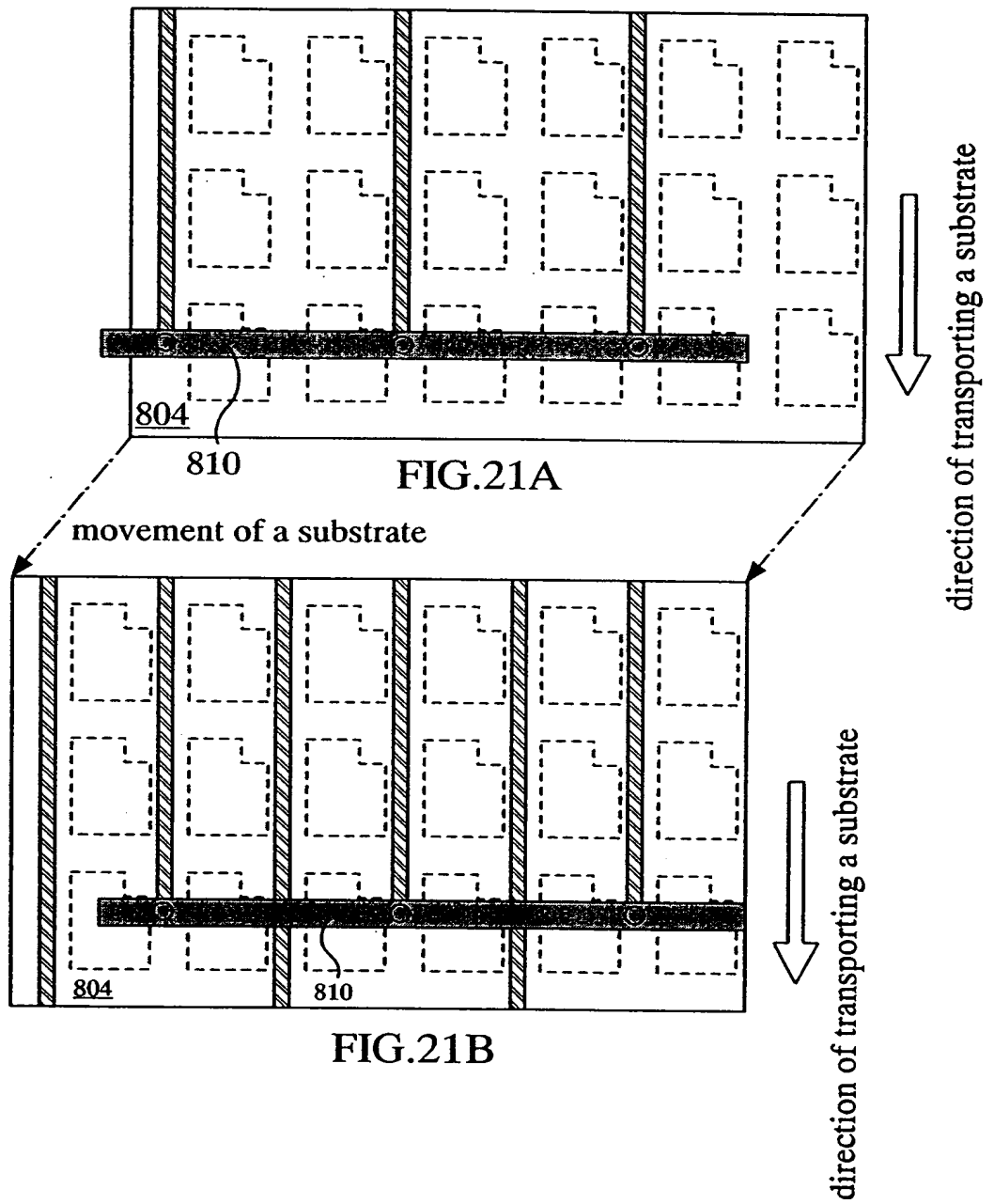


FIG. 19C





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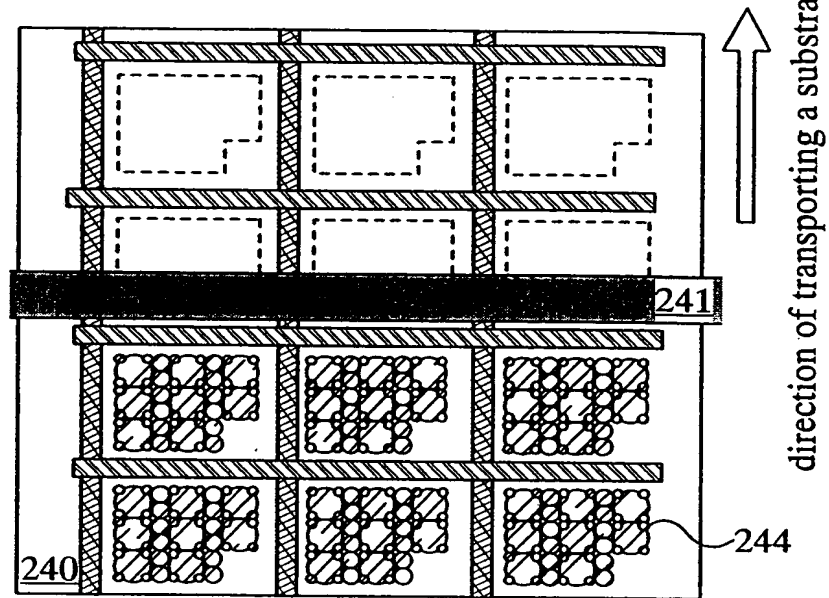


FIG. 22A

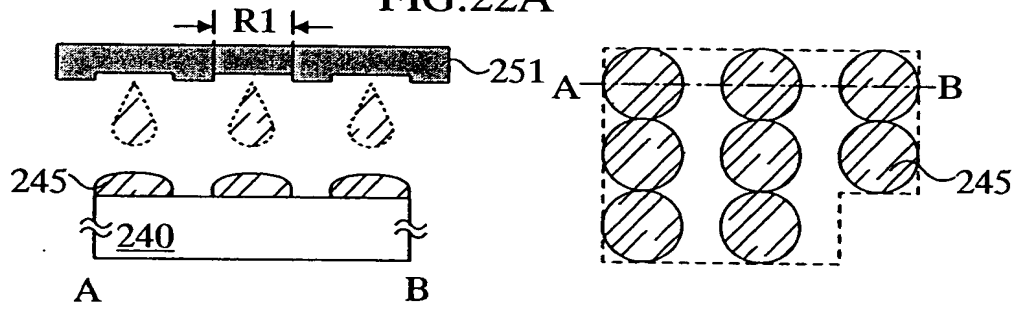


FIG. 22B

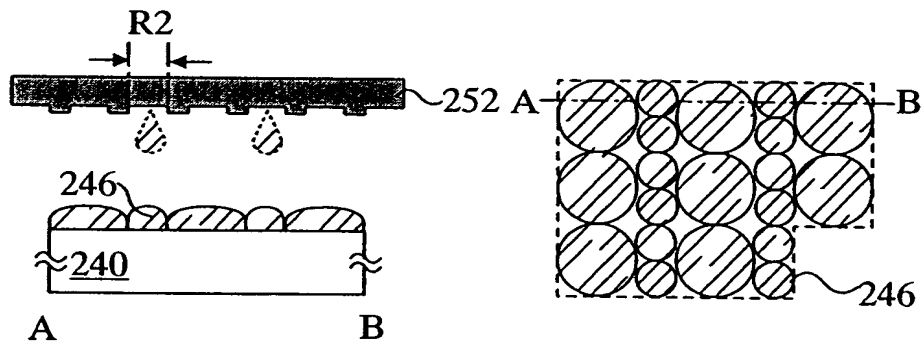


FIG. 22C

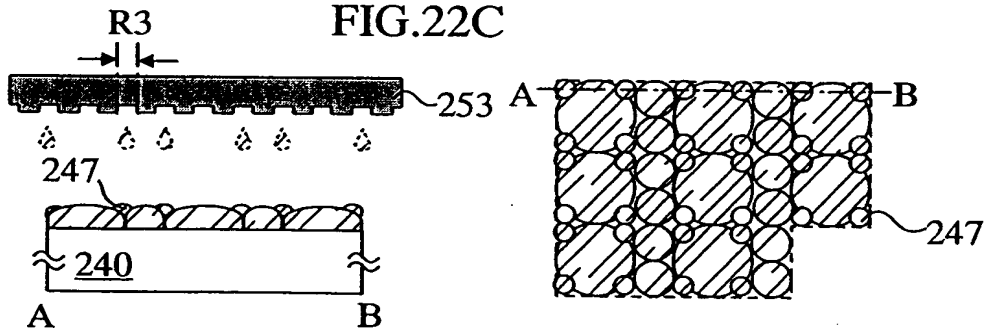


FIG. 22D

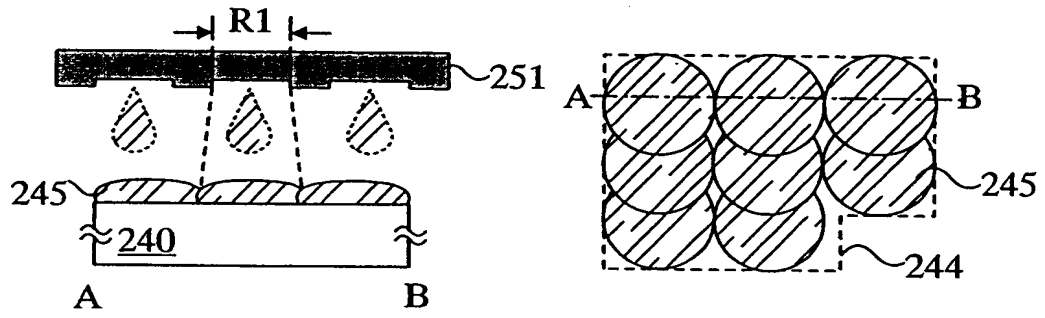


FIG. 23A

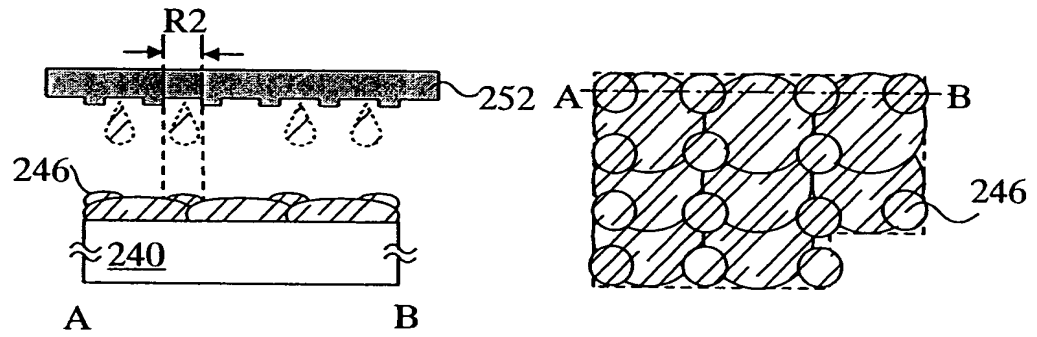


FIG. 23B

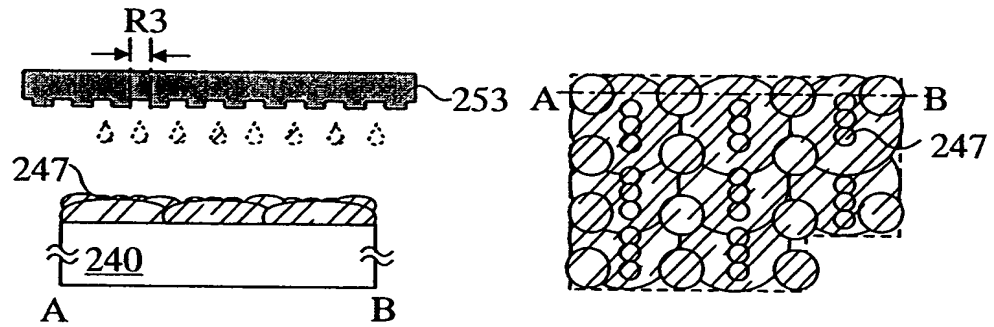


FIG. 23C

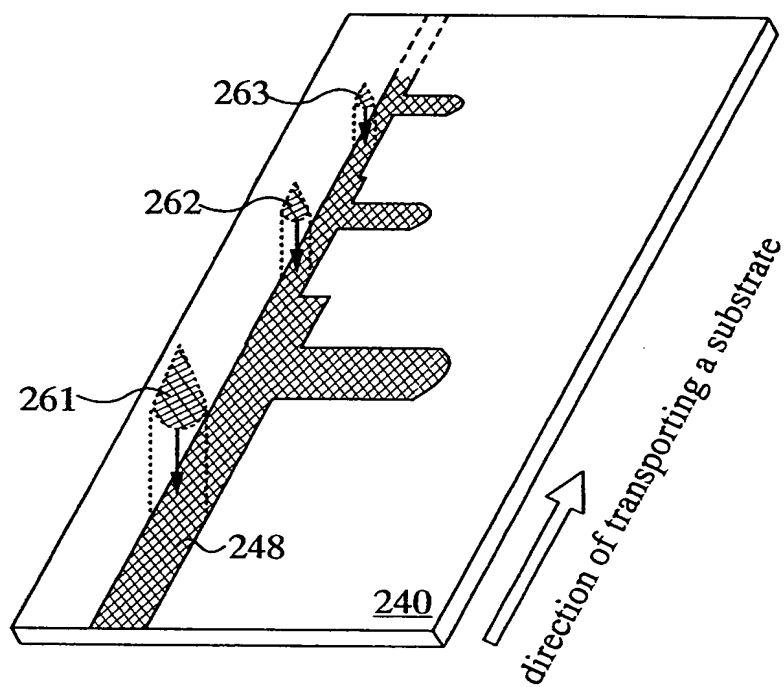


FIG.24

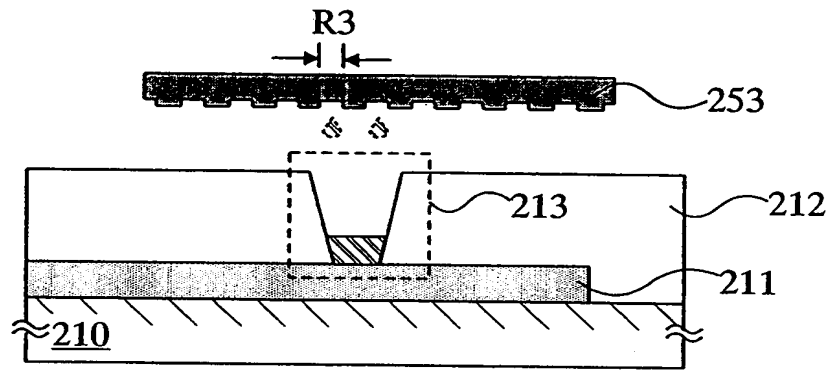


FIG. 25A

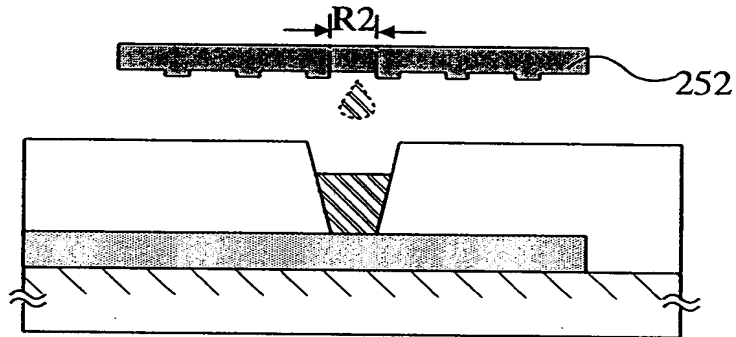


FIG. 25B

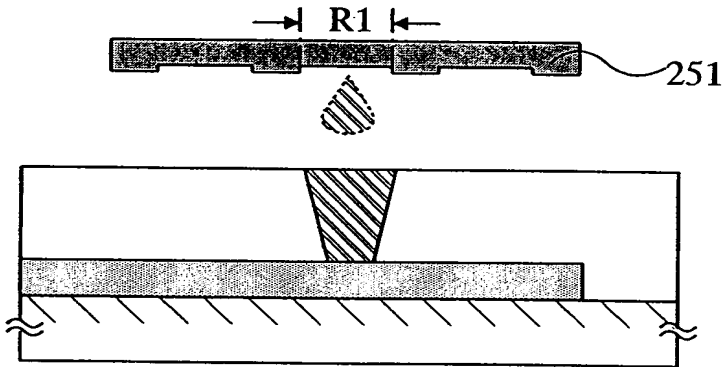


FIG. 25C

## DESCRIPTION OF NUMERALS

100:Substrate, 101-102:Gate electrode layer, 103:Gate insulating film, 104:Semiconductor film, 105:N-type semiconductor film, 106-109:Source or drain electrode, 110-113:Source or drain region, 114-115:Insulating film, 116:Island-like semiconductor film, 117:Channel region, 118:Island-like semiconductor film, 119:Channel region, 120:Wiring, 121-124:Source or drain wiring, 125:Conductor, 126:Pixel electrode, 127:Partition wall, 128:Organic compound layer, 129:Electron injecting electrode, 130:Passivation film, 131:Opposing substrate, 132:Titanium oxide film, 133:Silicon nitride film, 134:Insulating film, 141:Partition wall, 142:Organic compound layer, 143:Electron injecting electrode, 144:Passivation film, 145:Opposing substrate, 146:Light-emitting element, 150:Planarized film, 151:Planarized film, 152:Source or drain wiring, 161:Pillar insulator, 162:Liquid-shedding material, 163:Mask, 200:Light-emitting element, 210:Substrate, 211:Semiconductor or Conductor, 212:Insulator, 500:Glass substrate, 501:Nozzle, 502:Nano paste, 503:Conductor containing metal chains, 504:Film formed by organic ingredients, 626:Terminal electrode, 627:Anisotropic conductive film, 628:FPC, 652:Terminal portion, 654:Pixel TFT, 800:Circuit design tool, 801:Data of thin film pattern, 802:Computer, 805:Imaging means, 806:Image processing device, 807:Position information of alignment marker, 808:Controller, 816:XYθ stage, 817:Alignment marker, 819:Database, 2001:Housing, 2002:Display module, 2003:Main-screen, 2004:Modem, 2005:Receiver, 2006:Wireless remote control, 2007:Display portion, 2008:Sub-screen, 3001:Display panel, 3002:Operation panel, 3003:Connecting portion, 3004:Display portion, 3005:Voice output portion, 3006:Operation key, 3007:Power source switch, 3008:Voice input portion, 3009:Antenna, 3101:Main body, 3102:Display portion, 3103:Display portion, 3104:Memory medium, 3105:Operation switch, 3106:Antenna